



ENGINEERING DEPT.

REVISIONS | ECNT120150

PRODUCT SPECIFICATION

For 2.00 mm (.079") Board to Board Connectors of System CH11 SPEC.NO.: SPCH070B

**PAGE: 1/4** 

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

EIA 364 Test methods for electrical connectors

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part

design standards

3. APPLICABLE SERIES NO.: CH11\*\*1NB00-0M

CH11\*\*1NB00-TM

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

 $0.8 \text{ mm} (.031'') \sim 1.6 \text{ mm} (.063'')$ 

REVIEWED: <u>Eisley</u> APPROVED: <u>Sun</u> VERIFIED: <u>Jessie</u>.



ENGINEERING DEPT.	PRODUCT SPECIFICATION	SPEC.NO.:	SPCH070B
REVISIONS ECNT120150	For 2.00 mm (.079") Board to Board Connectors of System CH11	PAGE:	2/4

### 7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than $20 \text{ m}\Omega$
7.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than $5000 \text{ M}\Omega$

# 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT	
8.1	Pin retention force	Apply axial pull out force at 25 ± 3mm/min on the assembly in the housing	More than 0.8 Kgf	
9. EN	9. ENVIRONMENTAL PERFORMANCE:			

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Cold Resistance	-40°C ± 3°C, 96 hours	Appearance: No damage Contact resistance: $\Delta 20 \text{ m}\Omega$ change
9.2	Heat Resistance	105°C ± 3°C, 96 hours	Appearance: No damage Contact resistance: $\triangle 20 \text{ m}\Omega$ change
9.3	Temperature Cycling	5 cycles (1) -40 °C, 30 min. (2)Room temp. 10-15 min. (3) 105 °C, 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: $\triangle 20 \text{ m}\Omega$ change



ENGINEERING DEPT.<br/>REVISIONSPRODUCT SPECIFICATION<br/>For 2.00 mm (.079") Board to Board<br/>Connectors of System CH11SPEC.NO.: SPCH070B

	ITEM	TEST CONDITION	REQUIREMENT
9.4	Salt Spray	Temperature: 35 ± 3 °C	Appearance: No damage
		Solution: 5 ± 1%	Contact resistance:
		Spray time: 48 ± 4 hours	Less than twice of initial
		(Stamping before plated)	
		Spray time: 24 ± 4 hours	
		(Stamping after plated)	
		Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.	
		The specimens shall be suspended from the top using waxed twine, string or nylon thread.	
		The test only define the plating area, without plating area (as copper cross section) will not be defined.	
		(EIA 364-26B / MIL-STD-202 Method 101)	
9.5	Solder ability	Soldering time: $3 \pm 0.5$ sec	Minimum:
		Soldering pot: 240 ± 5 ° C	95% of immersed area
9.6	Resistance to	Soldering time: 7 ± 3 sec	No damage
	soldering heat	Soldering pot: 255 ± 5 °C	
		Refer Reflow temperature profile(11.1)	

10. OPERATING TEMPERATURE: -40°C to + 105°C



ENGINEERING DEPT.

PRODUCT SPECIFICATION

REVISIONS | ECNT120150

For 2.00 mm (.079") Board to Board Connectors of System CH11 SPEC.NO.: SPCH070B

**PAGE: 4/4** 

## 11. Recommended IR Reflow Temperature Profile:

### 11.1 Using Lead-Free Solder Paste

